

HSF

NOTES:

Current Rating: 2.0AMP
 Contact Resistance: 20mΩ Max
 Withstand Voltage: 500V AC/DC
 Insulation Resistance: 1000MΩ Min
 Operation Temperature: -40°C to +105°C

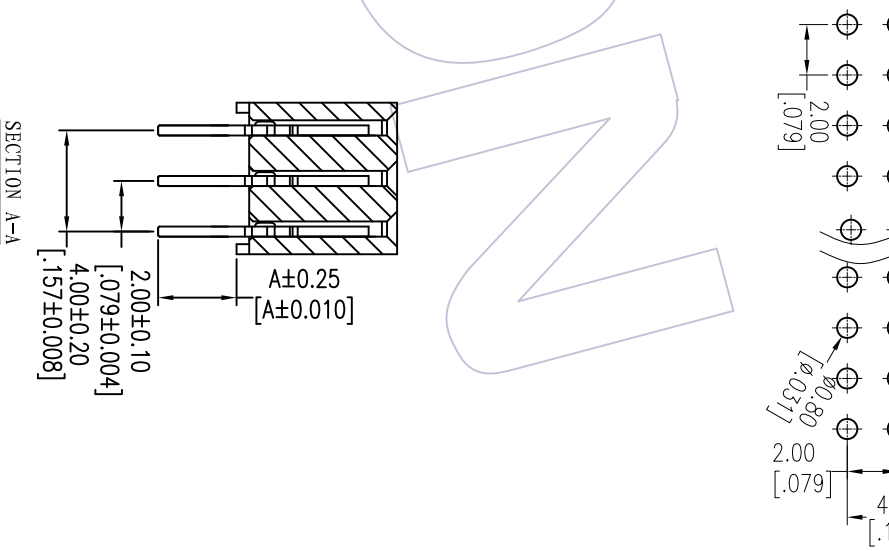
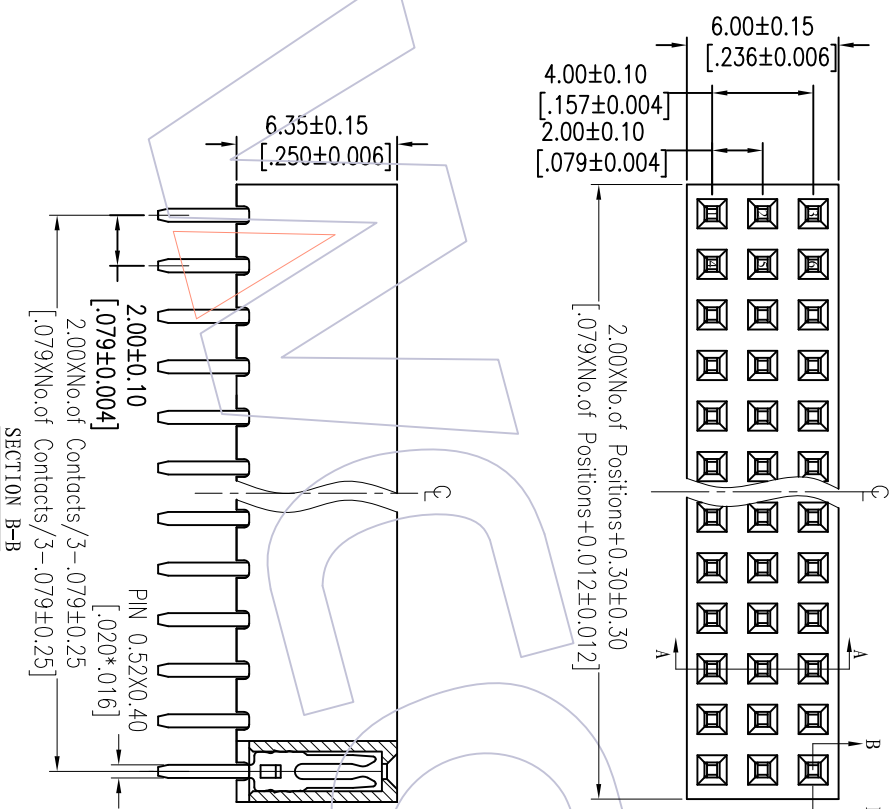
Contact Material: Phosphor Bronze
 Contact plating: Au Or Sn over Ni
 Insulator Material: LCP+30%G.F UL94V-0

Ordering Information

2263 - 3 XX S XX D Y N T X

No. of Pins per ROW: 02-40PIN
 Contact Plating: G3=10µ Gold, G4=15µ Gold, G5=30µ Gold
 Insulator: D=LCP, T=Tube
 Packing: S0=Gold Flash/Tin, S3=10µ Gold/Tin, S4=15µ Gold/Tin, S5=30µ Gold/Tin, SN=Tin, SM=Mate Tin

Item	Pitch	DIM A	Mating
Standard	2.00	3.1/2.4	1215/1220
Alternate			



Recommended P.C.B Layout(Top Side)
 (PCB BOARD TOLERANCE±0.05)

OPERATION	DRAW	DATE	SCALE	FIT	PART NO.
XX	Wang	2013/04/26	UNIT	mm	2263-3XXSXXDYNTX
XXX	CHECK	DATE	SIZE	A4	TITLE:
XXXX					FH2.00mm THREE ROW 180° DIP
Angle	APPROVE	DATE	SHEET	1/1	
± 3'			PROJ.		Customer NO.
DIM	TOL				

WCON

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REV	DATE	MODIFICATION DESCRIPTION	CHANGE
A2	2013/04/26	Modify drawing	---
A1	2012/11/07	Modificat the table: DIM A 3.15--3.1/2.4	---
A0	2012/07/23	NEW	---